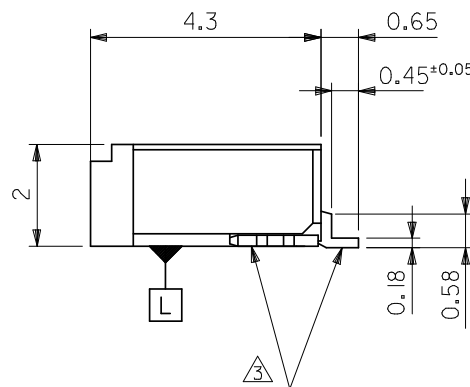
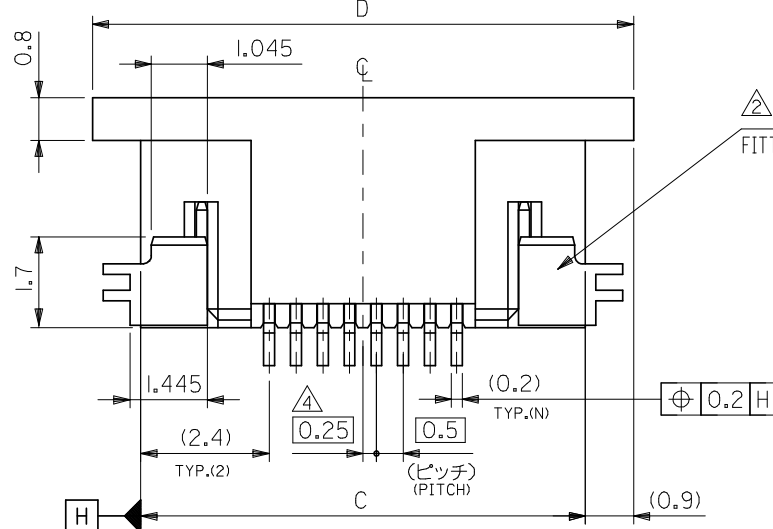
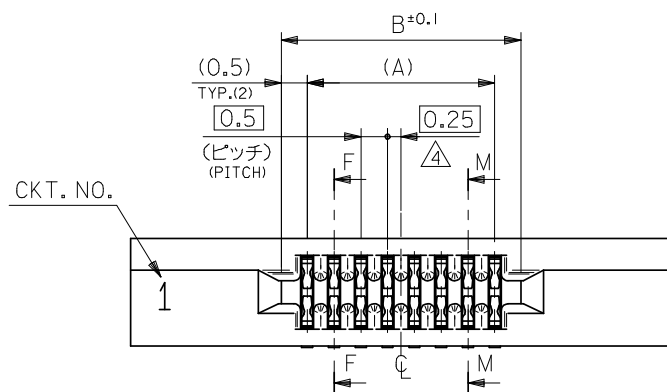
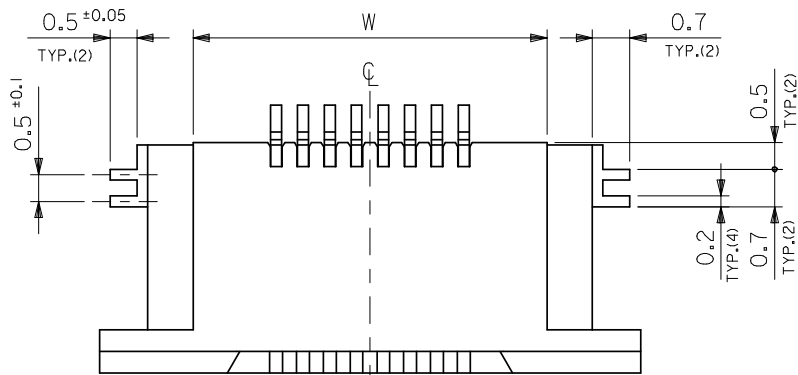
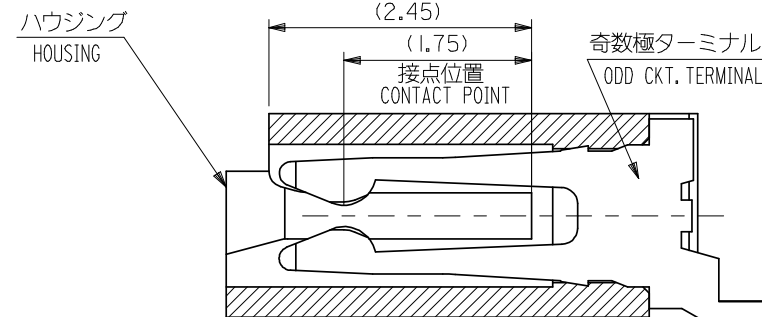
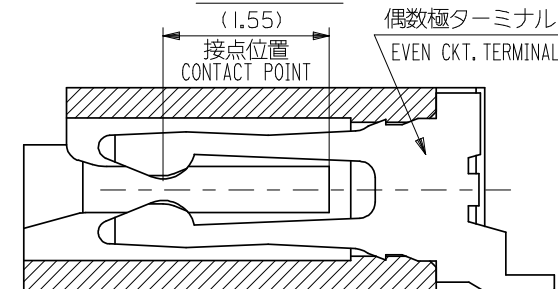




△金具
FITTING NAIL



SECT. M-M



SECT. F-F

注記(NOTES)

1. 使用材料 (MATERIAL)

ターミナル (TERMINAL): リン青銅

PHOSPHOR BRONZE ±0.2

錫ビスマスメッキ 1. 0マイクロメートル以上

TIN-BISMUTH I.O. MICROMETER MINIMUM

ニッケル下地 1. 0マイクロメートル以上

NICKEL (UNDER PLATING) I.O. MICROMETER MINIMUM

ハウジング (HOUSING): 46ナイロン (46NYLON), UL94V-0

金具 (FITTING NAIL): リン青銅

PHOSPHOR BRONZE ±0.2

錫メッキ 1. 0マイクロメートル以上

TIN I.O. MICROMETER MINIMUM

ニッケル下地 1. 0マイクロメートル以上

NICKEL (UNDER PLATING) I.O. MICROMETER MINIMUM

△ パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB. PATTERN.)

ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L

に対し上方向 0.1MAX. 下方向 0.15MAX. とする。

MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L

UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.

偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)

5. 本製品は 52689-***40 の鉛フリー品である。

THIS PRODUCT IS LEAD FREE 52689-***40.

MODEL NO. 52689-***49

GENERAL TOLERANCES
(UNLESS SPECIFIED)

DIMENSION STYLE
MM ONLY

SCALE

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

10 UNDER ±0.2

10 OVER 30 UNDER ±0.25

30 OVER ±0.3

ANGULAR ±3 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

H. KAWABATA '04/02/03

CHECKED BY DATE

K. TOJO '04/02/03

APPROVED BY DATE

M. SASAO '04/02/03

MATERIAL NO.

SEE SHEET 2

0.5 FPC CONN NON ZIF
HSG ASSY FOR SMT(R/A)
-LEAD FREE-

MOLEX INCORPORATED

SD-52689-034

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REVISED
EC NO: J2008-4308
DRWN: WABEI
CHKD: THARUYAMA
APPR: NUKITA

DESCRIPTION
REV

B

F

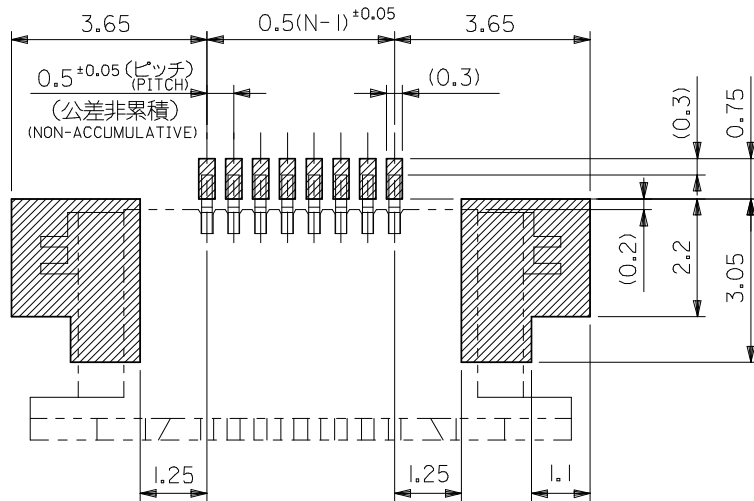
E

D

C

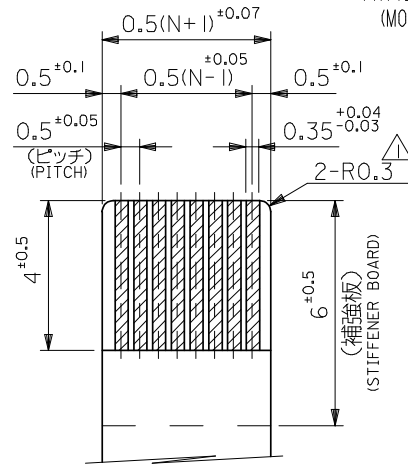
B

A



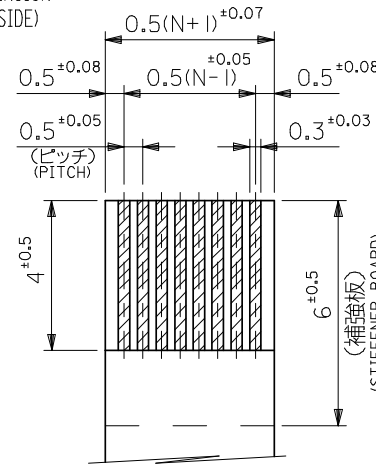
参考基板レイアウト
(マウント面)

REFERENCE P.C.BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合F P C推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合F F C推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

F P Cについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

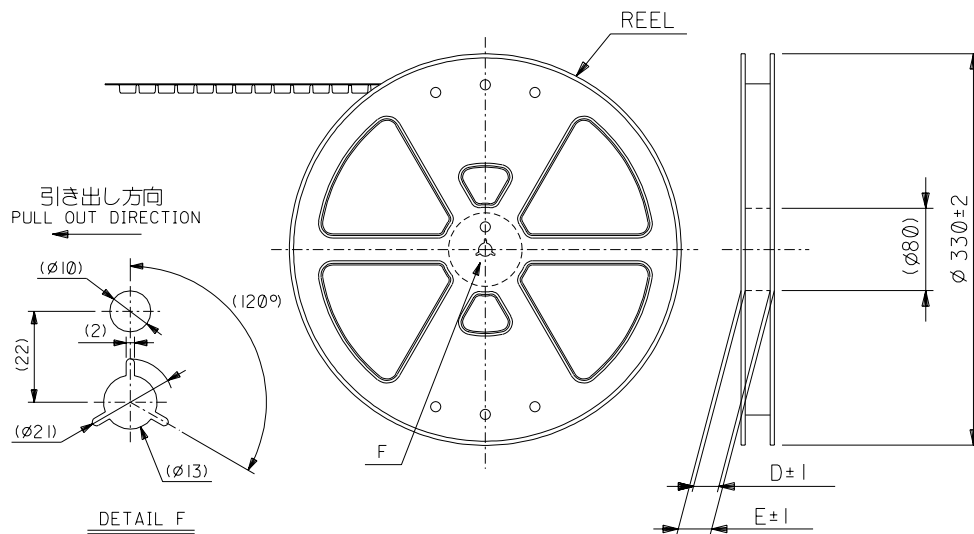
ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

- △ R0.3は、F P Cの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
17.1	20.6	18.8	15.0	14.0	-2987	-2949	29
16.6	20.1	18.3	14.5	13.5	-2887	-2849	28
16.1	19.6	17.8	14.0	13.0	-2787	-2749	27
15.6	19.1	17.3	13.5	12.5	-2687	-2649	26
15.1	18.6	16.8	13.0	12.0	-2587	-2549	25
14.6	18.1	16.3	12.5	11.5	-2487	-2449	24
14.1	17.6	15.8	12.0	11.0	-2387	-2349	23
13.6	17.1	15.3	11.5	10.5	-2287	-2249	22
13.1	16.6	14.8	11.0	10.0	-2187	-2149	21
12.6	16.1	14.3	10.5	9.5	-2087	-2049	20
12.1	15.6	13.8	10.0	9.0	-1987	-1949	19
11.6	15.1	13.3	9.5	8.5	-1887	-1849	18
11.1	14.6	12.8	9.0	8.0	-1787	-1749	17
10.6	14.1	12.3	8.5	7.5	-1687	-1649	16
10.1	13.6	11.8	8.0	7.0	-1587	-1549	15
9.6	13.1	11.3	7.5	6.5	-1487	-1449	14
9.1	12.6	10.8	7.0	6.0	-1387	-1349	13
8.6	12.1	10.3	6.5	5.5	-1287	-1249	12
8.1	11.6	9.8	6.0	5.0	-1187	-1149	11
7.6	11.1	9.3	5.5	4.5	-1087	-1049	10
7.1	10.6	8.8	5.0	4.0	-0987	-0949	9
6.6	10.1	8.3	4.5	3.5	-0887	-0849	8
6.1	9.6	7.8	4.0	3.0	-0787	-0749	7
5.6	9.1	7.3	3.5	2.5	-0687	-0649	6
5.1	8.6	6.8	3.0	2.0	52689-0587	52689-0549	5

52689-***49		W	D	C	B	A	EMBOSSED TAPE		MATERIAL NO.	極数 CKT.	
MODEL NO.							ORDER No. オーダー番号				
GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY			SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
			DRAWN BY H. KAWABATA		DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-					
UNDER		±0.2	CHECKED BY K. TOJO		DATE '04/02/03						
VER 30 UNDER		±0.25	APPROVED BY M. SASAO		DATE '04/02/03						
VER		±0.3	MATERIAL NO.		DOCUMENT NO.						
ULAR ±3 °			SEE TABLE			SD-52689-034			SHEET NO. 2 OF 2		
AFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



5. 材料 キャリアテープ: ポリプロピレン (PP)
 トップテープ: PET, PE, PEF
 リール: ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE: POLYPROPYLENE
TOP TAPE: PET, PE, PEF
REEL: POLYSTYRENE (PS)
<RECYCLE MATERIAL CONTAINED>

6. 本製品は52689-**-93の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52689-**-93.

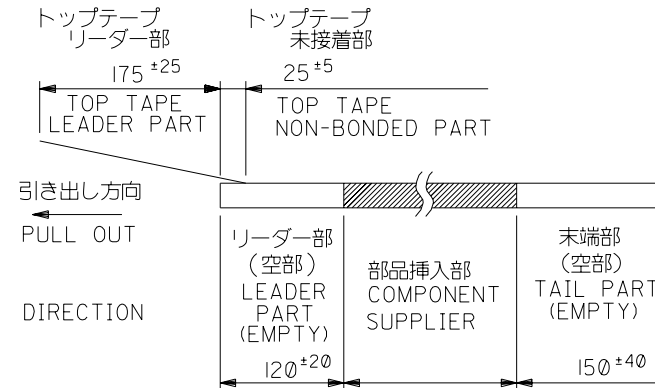
7. FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フォルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION :
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

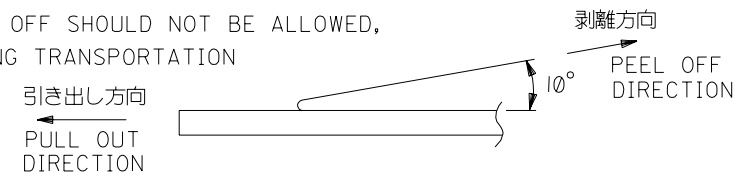
注記 NOTES

- 製品詳細寸法については図面 SD-52689-034 を参照下さい。
RE DETAILED DIMENSION, SEE SD-52689-034.
- 梱包数量: 1000個/リール
NUMBER OF CONNECTORS: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

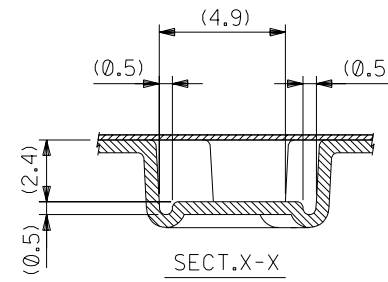
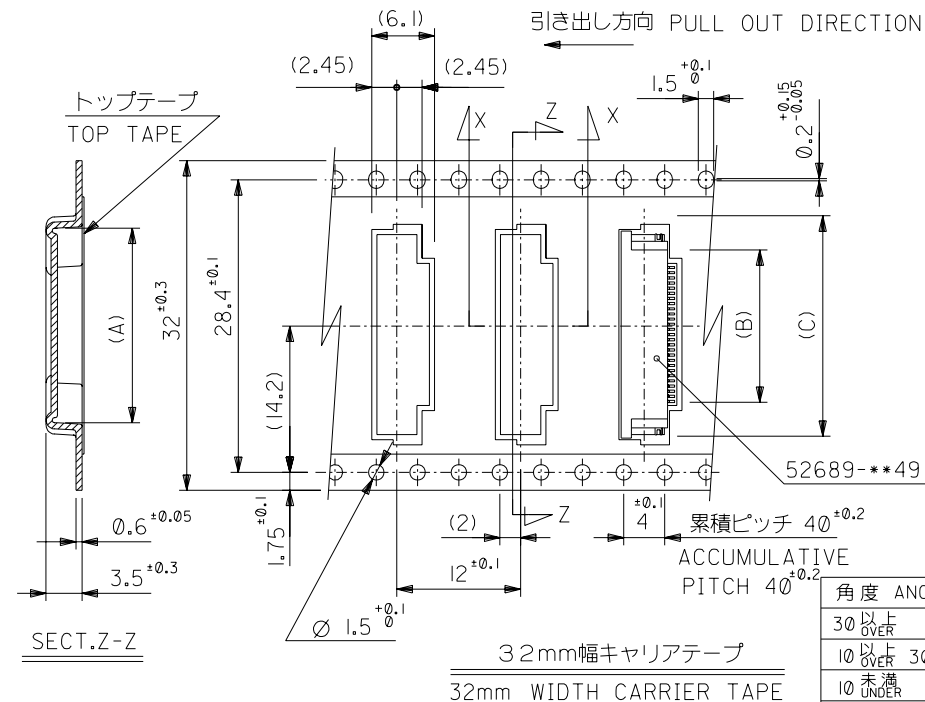
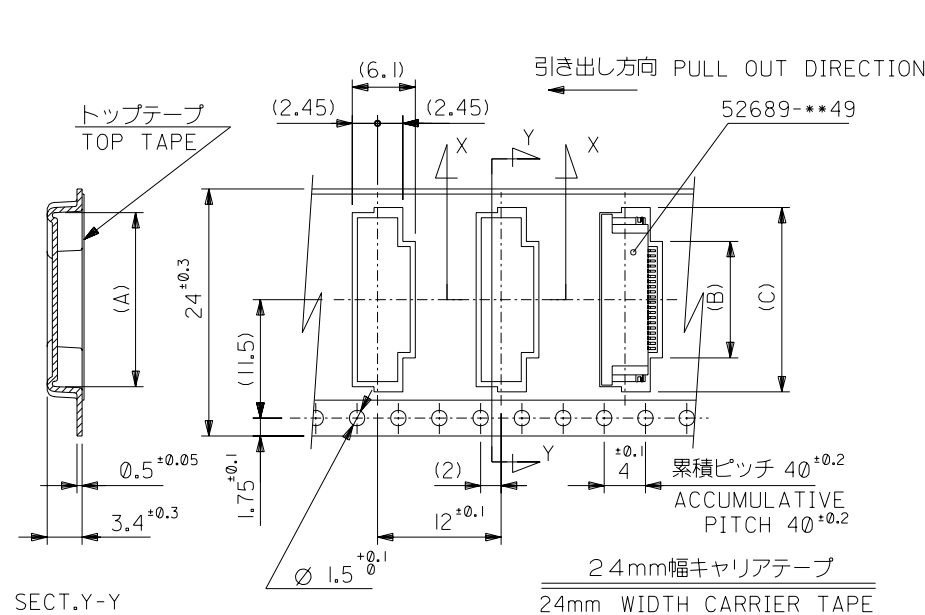


- トップテープの剥離強度: (剥離方向は下図参照)
0.1~1.3N {10~130gf}
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
0.1~1.3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



				材料 MATERIAL	注記参照 SEE NOTES	MOLEX-JAPAN CO., LTD. molex 日本モレックス株式会社	
				仕上げ FINISH	—	REVISE ONLY ON CAD SYSTEM	
				適用電線範囲 WIRE RANGE	—	TITLE 名称 0.5 FPC Conn NON ZIF	
				被覆外径 INS. RANGE	—	Hsg Assy SMT RA	
				DRAWN BY '04/02/03 H.KAWABATA	CHK'D BY '04/02/03 K.TOJO	Embstp Pkg -LEAD FREE-	
				APPRO'D BY '04/02/03 M.SASAO	尺度 SCALE	DWG. NO. (SHEET 1 OF 3) REV	
				記号 LTR	変更内容 REVISION RECORD	SD-52689-035	
				DR. CHK.	日付 DATE	0	
				新規作成 RELEASED (J2004-2222)	04/02/27		
				一般公差 GENERAL TOLERANCES	0		



	32	37.4	33.4	22.4	15.8	21.4	52689 -3087	30	
				21.9	15.3	20.9	-2987	29	
				21.4	14.8	20.4	-2887	28	
				20.9	14.3	19.9	-2787	27	
				20.4	13.8	19.4	-2687	26	
				19.9	13.3	18.9	-2587	25	
				19.4	12.8	18.4	-2487	24	
				18.9	12.3	17.9	-2387	23	
	24	29.4	25.4	17.9	11.3	16.9	-2187	21	
				17.4	10.8	16.4	-2087	20	
				16.9	10.3	15.9	-1987	19	
				16.4	9.8	15.4	-1887	18	
				15.9	9.3	14.9	-1787	17	
				15.4	8.8	14.4	-1687	16	
				14.9	8.3	13.9	-1587	15	
				14.4	7.8	13.4	-1487	14	
				13.9	7.3	12.9	-1387	13	
				13.4	6.8	12.4	-1287	12	
12.9				6.3	11.9	-1187	11		
12.4				5.8	11.4	-1087	10		
				11.9	5.3	10.9	-0987	9	
				11.4	4.8	10.4	-0887	8	
				10.9	4.3	9.9	-0787	7	
				10.4	3.8	9.4	-0687	6	
				9.9	3.3	8.9	52689 -0587	5	

角度 ANGLE	±3°
30°以上 OVER	±0.5
10°以上 30°未満 OVER UNDER	±0.25
10°未満 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

52689-***87	新規作成 RELEASED (J2004-2222)	04/02/03
記号 LTR	変更内容 REVISION RECORD	DR. CHK. 日付 DATE
材料 MATERIAL		
SHEET 1 OF 3参照 REFER TO SHEET 1 OF 3		
仕上げ FINISH		
適用電線範囲 WIRE RANGE		
被覆外径 INS. RANGE		
DRAWN BY 04/02/03 H.KAWABATA		
CHK'D BY 04/02/03 K.TOJO		
APP'D BY 04/02/03 M.SASAO		
尺度 SCALE		

molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
REVISE ONLY ON CAD SYSTEM	
TITLE 名称 0.5 FPC Conn NON ZIF Hsg Assy SMT RA Embstp Pkg -LEAD FREE-	
DWG. NO. (SHEET 2 OF 3)	REV
SD-52689-035	0

